

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 843.37558VX2	SERIAL NO.
	APPLICANT M. FUNABASHI	
	FILING DATE July 12, 2001	GROUP 2825

1c903 U.S. PTO
09/02/02
07/12/01

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AM	AA	4,239,661	12/16/80	Muraoka et al.	438 ←252→ -541→ 471	
	AB	4,958,061	09/18/90	Wakabayashi et al.	219 411	
	AC	5,286,678	02/15/94	Rastogi	438 ←437→ -200→ 301	
	AD	5,288,651	02/22/94	Nakazawa	438 ←437→ -34→ 145	
	AE	5,290,361	03/01/94	Hayashida et al.	134 2	
	AF	5,447,568	09/05/95	Hayakawa et al.	118 ←437→ -187→ 715	
	AG	5,466,389	11/14/95	Ilardi et al.	510 ←252→ -156→ 175	
	AH	5,783,495	07/21/98	Li et al.	438 738	
	AI	5,972,862	10/26/99	Torii et al.	510 175	
	AJ	5,855,811	01/05/99	Grieger et al.	252 79.3	
	AK	5,679,171	10/1997	Saga et al.	134 3	
	AL	6,096,650	08/2000	Robinson et al.	438 689	

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
AM	AM	03-109732-A	05/1991	Japan	H01L 21/304		
		04-101418-A	04/1992	Japan	H01L 21/304		
		07-153728-A	06/1995	Japan	H01L 21/304		
		08-250461-A	09/1996	Japan	H01L 21/304		
		08-306650-A	11/1996	Japan	H01L 21/304		
		08-306651-A	11/1996	Japan	H01L 21/304		
		09-286999-A	11/1997	Japan	H01L 21/304		

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AM	AN	Oimet et al., "Defect Reduction and Cost Savings through Re-Inventing RCA Cleans", <i>IEEE/SEMI Advanced Semiconductor Manufacturing Conference</i> (1996), p. 308-313
	AO	Watanabe et al., "Influence of particles/impurity metals in RCA cleaning solutions on surface contamination", <i>International Symposium on Semiconductor Manufacturing</i> (1994), pp. 99-102
	AP	Osaka and Hattori, "Influence of Initial Wafer Cleanliness on Metal Removal Efficiency in Immersion SC-1 Cleaning: Limitation of Immersion-Type Wet Cleaning", <i>IEEE Trans. on Semiconductor Manufacturing</i> , Vol. 11, No. 1 (02/1998), pp. 20-24
	AQ	Ridley, Sr. et al., "Advanced Aqueous Wafer Cleaning in Power Semiconductor Device Manufacturing", <i>IEEE/SEMI Adv. Semiconductor Man. Conf.</i> (1998), pp. 235-242
	AR	"Improved Organic Clean for Removing Contaminants on Semiconductor Wafer Surfaces", <i>IBM Tech. Dis. Bulletin</i> , March 1985
	AS	"Improvements to MOS Retention Time Based Tests", <i>IBM Tech. Dis. Bulletin</i> , May 1984
Examiner <i>J. H. Mahan</i>		Date Considered 11-8-2001